	Hits	Search Text	DBs
35	749	((substrate or wafer) same (ITO or (transparent near4 conductive near6 layer) or (indium near4 tin near4 oxide)) same (resist or photoresist) same (lithography or expos$4 or irradiat$4 or illuminat$4)) and develop$4 and (etch$4 near28 (dry or RIE or plasma))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
36	79	S33 and S35	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
37	45	S36 NOT S34	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB
38	76	((substrate or wafer) same (resist or photoresist) same (methacrylate or acrylate or polycarbonate or polyimide) same (lithography or expos$4 or irradiat$4 or illuminat$4)) and (develop$4 same (pattern or mask) same (plat$4 or metalliz$5)) and ((plat$4 or metallization) same strip$4 same (base or basic or developer))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB